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Reliability of systems, equipment and components

Part 16. Guide to stress screening

**Section 16.1 Repairable items
manufactured in lots**

ICS 29.020

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Contents

	Page
Committees responsible	Inside front cover
National foreword	iii
Introduction	1
Guide	
1 Scope	4
2 Normative references	4
3 Definitions	6
4 Symbols	8
5 General description	8
6 Planning	11
7 Pilot-production screening	20
8 Mature production screening	21
Annexes	
A (informative) Stress conditions: general information	24
B (informative) Stress conditions: temperature	27
C (informative) Stress conditions: vibration and bump	31
D (informative) Stress conditions: humidity	37
E (informative) Stress conditions: operational stress	40
F (informative) Bimodal distributions — Weibull plotting and analysis	42
G (informative) Evaluation of the failure-free period and the average screening duration	48
H (informative) Worked-through example	59
Tables	
A.1 Stress types — indication of cost of application	25
H.1 Relations between the sensitivity of flaws and stresses	62
H.2 Observed failure ranks and times to first failure for the pilot production	66
H.3 Revised rank values	69
Figures	
1 The conceptual difference between reliability screening and growth	2
2 Typical flow for the design and modifications of reliability stress screening processes for repairable items	3
3 A typical flow of hardware items from the component manufacturer to the end user	5
4 Reliability stress screening of repairable items	9
5 Dependency of categories of failures	11
6 Elements of stress conditioning	12
7 The item must show a failure-free period T_M before being accepted	13
8 Time graphs for determination of the failure-free period	16
F.1 The S-curve for a bimodal Weibull distribution mixed by	
$F_1(t) = 1 - e^{-\left(\frac{t}{30}\right)^{1.5}}$ and $F_2(t) = 1 - e^{-\left(\frac{t}{60\,000}\right)^{1.5}}$	43
F.2 Estimation of p , k_1 and b_1 for the purpose of reliability screening optimization	44
F.3 The c.d.f.'s for bimodal exponential distributions	46
F.4 The hazard rate function for bimodal exponential distributions	47
G.1 The basic system	48
G.2 An item with n weak components surviving the screening period T_M	50